

ABSTRACT

Disclosed is a moisture-curing type curable resin composition containing: a curable resin intramolecularly having
5 a silicon-containing functional group; and a Lewis acid or a complex of the Lewis acid as a curing catalyst, the Lewis acid being selected from the group consisting of metal halides and boron halides, which is rapidly cured at room temperature. The silicon-containing functional group is represented by general
10 formula: $-SiX^1X^2X^3$ or $-SiR^1 X^1 X^2$ (wherein, X^1 , X^2 and X^3 respectively represent a hydrolytic group and may be the same as or different from each other, and R^1 represents a substituted or unsubstituted organic group having 1 to 20 carbons). If the silicon-containing functional group is $-SiR^1 X^1 X^2$, the curable
15 resin further contains intramolecularly a polar component that is one of urethane, thiourethane, urea, thiourea, substituted urea, substituted thiourea, amide, and sulfide bonds, and hydroxyl, secondary amino and tertiary amino groups. Two-part type adhesive is constitutable with separating the curable resin
20 from the curing catalyst.